

Title (en)
Polishing apparatus

Title (de)
Poliervorrichtung

Title (fr)
Appareil de polissage

Publication
EP 0860238 A2 19980826 (EN)

Application
EP 98103139 A 19980223

Priority
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Abstract (en)
A polishing apparatus is used for polishing a workpiece such as a semiconductor wafer to a flat mirror finish. The polishing apparatus comprises a turntable having a polishing surface, and a top ring having a pressing surface for holding a workpiece to be polished and pressing the workpiece against the polishing surface of the turntable. At least one of the polishing surface of the turntable and the pressing surface of the top ring is a curved surface such as a convex surface or a concave. <IMAGE>

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B24B 37/04; **H01L 21/304**

IPC 8 full level
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CPC (source: EP KR US)
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Cited by
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DE FR

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